Patent claims

1. A device for connecting the terminal pins of a package for an optical transmitting and/or receiving device to a printed circuit board, having:

- a package with a base plate,
- at least two terminal pins, which respectively protrude perpendicularly from the base plate of the package, at least one of the terminal pins being a high-frequency terminal pin which transmits a high-frequency signal,
- a flexible conductor arrangement with a plurality of interconnects, the conductor arrangement providing an electrical connection between the terminal pins of the package and electrical contacts of a printed circuit board, and
- contact regions of the conductor arrangement for the electrical connection of the interconnects respectively on the one hand to a terminal pin and on the other hand to a contact of a printed circuit board,
- at least that region of the conductor arrangement which provides a connection to the at least one high-frequency terminal pin lying in a plane which is aligned substantially perpendicularly to the plane of the base plate.

2. The arrangement as claimed in claim 1, the contact regions of the conductor arrangement which are connected to a high-frequency terminal pin having an elongate form in the axial direction of the terminal pins.

3. The arrangement as claimed in claim 1 or 2, the conductor arrangement having a first part and a second part, which is movable in relation to said first part, and the region of the conductor arrangement which provides a connection to the at least one high-frequency terminal pin being provided by the

first part of the conductor arrangement, while the second part has interconnects for low-frequency signals.

4. The arrangement as claimed in claim 3, the first part of the conductor arrangement having two contact regions, which contact two additionally arranged high-frequency pins of the package.

5. The arrangement as claimed in claim 3 or 4,

- the base plate of the package being formed in an electrically conducting manner,
- one or more contacting elements protruding from the base plate of the package perpendicularly to the latter, and
- the first part of the conductor arrangement having a contact region which is connected to a reference potential and is connected to the contacting element or the contacting elements.

6. The arrangement as claimed in claim 5, the contact region which is connected to a reference potential being arranged on a side of the conductor arrangement which is opposite from the side which has the contact regions connected to the high-frequency terminals, so that, in the region adjacent to the base plate, the first part of the conductor arrangement runs between at least one high-frequency terminal pin and the contacting plate.

7. The arrangement as claimed in claim 3, the first and the second part of the conductor arrangement being bent differently in the direction of the package, starting from a common end region which serves for the contacting of an assigned printed circuit board.

8. The arrangement as claimed in claim 7, the second part of the conductor arrangement forming two bent lateral arms, of which one in each case runs to the side of the first part of the conductor arrangement, and the ends of the two arms facing the bottom region being connected to each other by a transverse region running substantially perpendicularly to the arms and bearing contact regions for the contacting of further terminal pins.

9. The arrangement as claimed in claim 8, the transverse region of the conductor arrangement being oriented parallel to the base plate.

10. The arrangement as claimed in claim 8, a thermistor being arranged on the transverse region of the conductor arrangement on the side facing the base plate and being pressed elastically against the base plate.

11. The arrangement as claimed in claim 1, the contact regions of the conductor arrangement which are connected to a high-frequency terminal pin being contact pads which are formed on the one surface of the planar conductor arrangement and are preferably elongate.

12. The arrangement as claimed in claim 3, the contact regions of the second part of the conductor arrangement being formed as via holes.

13. The arrangement as claimed in claim 1, the connection of the contact regions of the conductor arrangement to the terminal pins of the package respectively taking place by means of a soldered connection.

14. The arrangement as claimed in claim 8, the two arms of the second part being bent in a U-shaped manner.

15. The arrangement as claimed in claims 3 and 7, the length of the interconnects of the first part being shorter than the length of the interconnects of the second part.

16. A conductor arrangement having:
- a number of interconnects on a flexible dielectric;
- a first part, which contains at least one interconnect for a high-frequency signal;
- a second part, which is movable in relation to the first part and contains at least one interconnect for a low-frequency signal,
- the two parts being bent in different ways, starting from a common end.

17. The conductor arrangement as claimed in claim 16, the first part of the conductor arrangement having at its end remote from the common end contact regions which allow the connection of terminal pins in an alignment such that the contact regions run in the axial direction of the terminal pins.

18. The conductor arrangement as claimed in claim 16, the second part of the conductor arrangement forming two bent lateral arms, of which one in each case runs to the side of the first part of the conductor arrangement, and the ends of the two arms being connected to each other by a transverse region running substantially perpendicularly to the arms and having at least one contact region.

19. The conductor arrangement as claimed in claim 18, the two arms of the second part being bent in a U-shaped manner.

20. The conductor arrangement as claimed in claim 16, the length of the interconnects of the first part being shorter than the length of the interconnects of the second part.